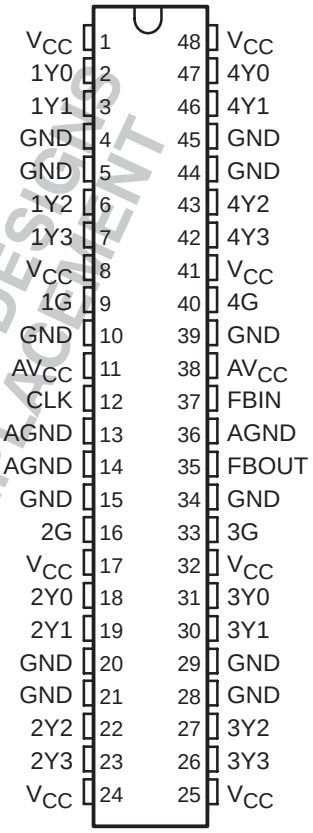
- **Use *CDCVF2510A* as a Replacement for this Device**
- **Phase-Lock Loop Clock Distribution for Synchronous DRAM Applications**
- **Distributes One Clock Input to Four Banks of Four Outputs**
- **Separate Output Enable for Each Output Bank**
- **External Feedback Pin (FBIN) Is Used to Synchronize the Outputs to the Clock Input**
- **No External RC Network Required**
- **Operates at 3.3-V V_{CC}**
- **Packaged in Plastic 48-Pin Thin Shrink Small-Outline Package**

DGG PACKAGE
(TOP VIEW)



description

The CDC516 is a high-performance, low-skew, low-jitter, phase-lock loop clock driver. It uses a phase-lock loop (PLL) to precisely align, in both frequency and phase, the feedback output (FBOUT) to the clock (CLK) input signal. It is specifically designed for use with synchronous DRAMs. The CDC516 operates at 3.3-V V_{CC} and is designed to drive up to five clock loads per output.

Four banks of four outputs provide 16 low-skew, low-jitter copies of the input clock. Output signal duty cycles are adjusted to 50 percent, independent of the duty cycle at the input clock. Each bank of outputs can be enabled or disabled separately via the 1G, 2G, 3G, and 4G control inputs. When the G inputs are high, the outputs switch in phase and frequency with CLK; when the G inputs are low, the outputs are disabled to the logic-low state.

Unlike many products containing PLLs, the CDC516 does not require external RC networks. The loop filter for the PLL is included on-chip, minimizing component count, board space, and cost.

Because it is based on PLL circuitry, the CDC516 requires a stabilization time to achieve phase lock of the feedback signal to the reference signal. This stabilization time is required following power up and application of a fixed-frequency, fixed-phase signal at CLK, as well as following any changes to the PLL reference or feedback signals. The PLL may be bypassed for test purposes by strapping AV_{CC} to ground.

The CDC516 is characterized for operation from 0°C to 70°C.

FUNCTION TABLE

INPUTS					OUTPUTS				
1G	2G	3G	4G	CLK	1Y (0:3)	2Y (0:3)	3Y (0:3)	4Y (0:3)	FBOUT
X	X	X	X	L	L	L	L	L	L
L	L	L	L	H	L	L	L	L	H
L	L	L	H	H	L	L	L	H	H
L	L	H	L	H	L	L	H	L	H
L	L	H	H	H	L	L	H	H	H
L	H	L	L	H	L	H	L	L	H
L	H	L	H	H	L	H	L	H	H
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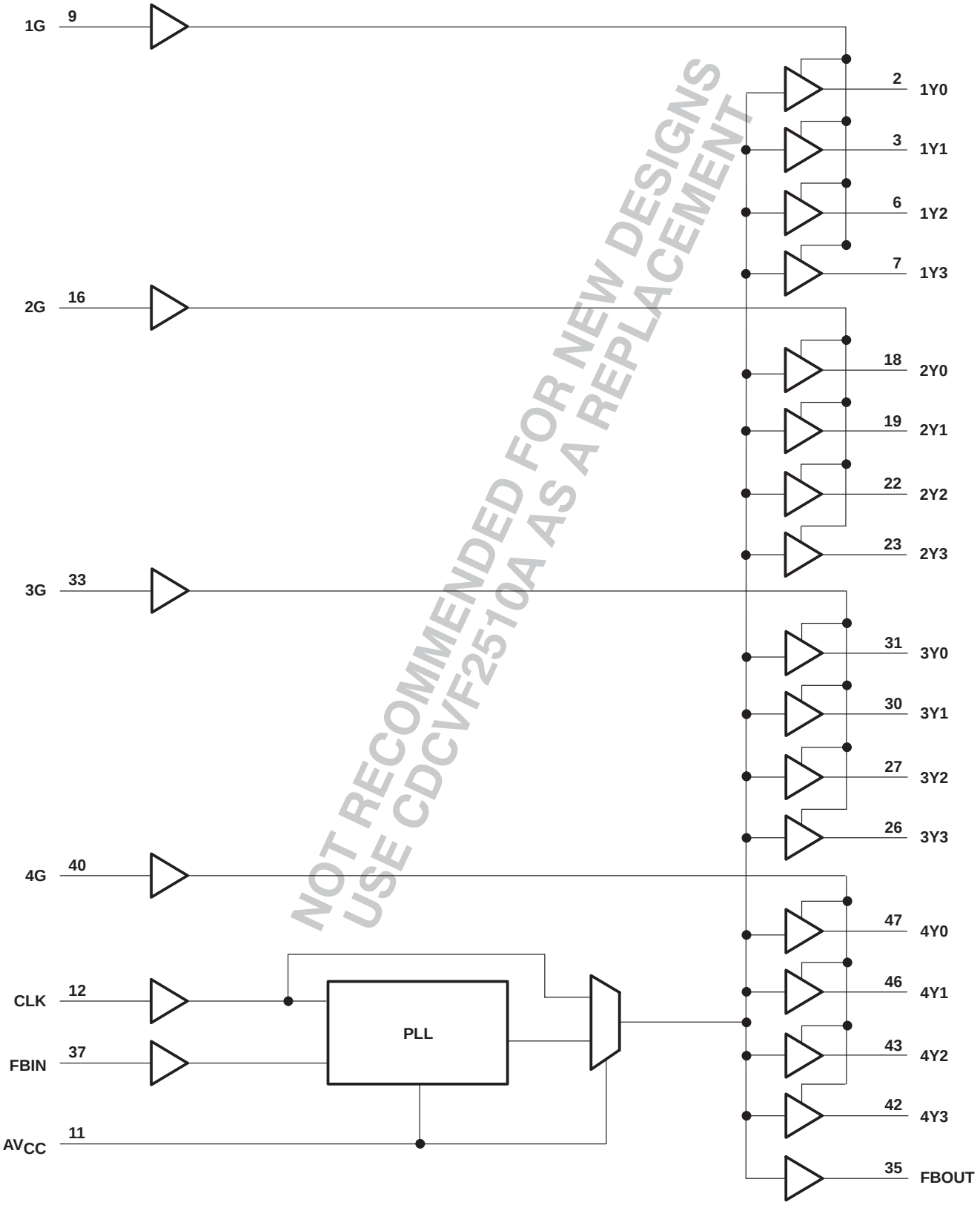
L	H	H	H	H	L	H	H	H	H
H	L	L	L	H	H	L	L	L	H
H	L	L	H	H	H	L	L	H	H
H	L	H	L	H	H	L	H	L	H
H	L	H	H	H	H	L	H	H	H
H	H	L	L	H	H	H	L	L	H
H	H	L	H	H	H	H	L	H	H
H	H	H	L	H	H	H	H	L	H
H	H	H	H	H	H	H	H	H	H

AVAILABLE OPTIONS

T_A	PACKAGE
	SMALL OUTLINE (PW)
0°C to 70°C	CDC516DGGR

functional block diagram



Terminal Functions

TERMINAL NAME	TERMINAL NO.	TYPE	DESCRIPTION
CLK	12	I	Clock input. CLK provides the clock signal to be distributed by the CDC516 clock driver. CLK is used to provide the reference signal to the integrated PLL that generates the clock output signals. CLK must have a fixed frequency and fixed phase for the PLL to obtain phase lock. Once the circuit is powered up and a valid CLK signal is applied, a stabilization time is required for the PLL to phase lock the feedback signal to its reference signal.
FBIN	37	I	Feedback input. FBIN provides the feedback signal to the internal PLL. FBIN must be hard-wired to FBOUT to complete the PLL. The integrated PLL synchronizes CLK and FBIN so that there is nominally zero phase error between CLK and FBIN.
1G	9	I	Output bank enable. 1G is the output enable for outputs 1Y(0:3). When 1G is low, outputs 1Y(0:3) are disabled to a logic-low state. When 1G is high, all outputs 1Y(0:3) are enabled and switch at the same frequency as CLK.
2G	16	I	Output bank enable. 2G is the output enable for outputs 2Y(0:3). When 2G is low, outputs 2Y(0:3) are disabled to a logic-low state. When 2G is high, all outputs 2Y(0:3) are enabled and switch at the same frequency as CLK.
3G	33	I	Output bank enable. 3G is the output enable for outputs 3Y(0:3). When 3G is low, outputs 3Y(0:3) are disabled to a logic-low state. When 3G is high, all outputs 3Y(0:3) are enabled and switch at the same frequency as CLK.
4G	40	I	Output bank enable. 4G is the output enable for outputs 4Y(0:3). When 4G is low, outputs 4Y(0:3) are disabled to a logic-low state. When 4G is high, all outputs 4Y(0:3) are enabled and switch at the same frequency as CLK.
FBOUT	35	O	Feedback output. FBOUT is dedicated for external feedback. It switches at the same frequency as CLK. When externally wired to FBIN, FBOUT completes the feedback loop of the PLL.
1Y(0:3)	2, 3, 6, 7	O	Clock outputs. These outputs provide low-skew copies of CLK. Outputs 1Y(0:3) are enabled via 1G. These outputs can be disabled to a logic-low state by deasserting the 1G control input.
2Y(0:3)	18, 19, 22, 26	O	Clock outputs. These outputs provide low-skew copies of CLK. Outputs 2Y(0:3) are enabled via 2G. These outputs can be disabled to a logic-low state by deasserting the 2G control input.
3Y(0:3)	31, 30, 27, 26	O	Clock outputs. These outputs provide low-skew copies of CLK. Outputs 3Y(0:3) are enabled via 3G. These outputs can be disabled to a logic-low state by deasserting the 3G control input.
4Y(0:3)	47, 46, 43, 42	O	Clock outputs. These outputs provide low-skew copies of CLK. Outputs 4Y(0:3) are enabled via 4G. These outputs can be disabled to a logic-low state by deasserting the 4G control input.
AV_{CC}	11, 38	Power	Analog power supply. AV_{CC} provides the power reference for the analog circuitry. In addition, AV_{CC} can be used to bypass the PLL for test purposes. When AV_{CC} is strapped to ground, the PLL is bypassed and CLK is buffered directly to the device outputs.
AGND	13, 14, 36	Ground	Analog ground. AGND provides the ground reference for the analog circuitry.
V_{CC}	1, 8, 17, 24, 25, 32, 41, 48	Power	Power supply
GND	4, 5, 10, 15, 20, 21, 28, 29, 34, 39, 44, 45	Ground	Ground

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} . . . . . −0.5 V to 4.6 V
Input voltage range, V_I (see Note 1) . . . . . −0.5 V to 6.5 V
Voltage range applied to any output in the high or low state, V_O (see Notes 1 and 2) . . . . . −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0) . . . . . −50 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{CC}) . . . . . ±50 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) . . . . . ±50 mA
Continuous current through each V_{CC} or GND . . . . . ±100 mA
Maximum power dissipation at T_A = 55°C (in still air) (see Note 3) . . . . . 0.85 W
Storage temperature range, T_{stg} . . . . . −65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. This value is limited to 4.6 V maximum.
3. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the *Package Thermal Considerations* application note in the *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002.

recommended operating conditions (see Note 4)

		MIN	MAX	UNIT
V_{CC}	Supply voltage	3	3.6	V
V_{IH}	High-level input voltage	2		V
V_{IL}	Low-level input voltage		0.8	V
V_I	Input voltage	0	V_{CC}	V
I_{OH}	High-level output current		−20	mA
I_{OL}	Low-level output current		20	mA
T_A	Operating free-air temperature	0	70	°C

NOTE 4: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		V_{CC}	MIN	TYP‡	MAX	UNIT
V_{IK}	I_I = −18 mA		3 V			−1.2	V
V_{OH}	I_{OH} = −100 µA		MIN to MAX	V_{CC} −0.2			V
	I_{OH} = −20 mA		3 V	2.4			
V_{OL}	I_{OL} = 100 µA		MIN to MAX			0.2	V
	I_{OL} = 20 mA		3 V			0.55	
I_I	V_I = V_{CC} or GND		3.6 V			±5	µA
I_{CC}§	V_I = V_{CC} or GND	I_O = 0, Outputs: low or high	3.6 V			20	µA
ΔI_{CC}	One input at V_{CC} − 0.6 V,	Other inputs at V_{CC} or GND	3.3 V to 3.6 V			500	µA
C_i	V_I = V_{CC} or GND		3.3 V		4		pF
C_o	V_O = V_{CC} or GND		3.3 V		6		pF

‡ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
§ For I_{CC} of AV_{CC}, see Figure 5. For dynamic digital I_{CC}, see Figure 6.

timing requirements over recommended ranges of supply voltage and operating free-air temperature

		MIN	MAX	UNIT
f_{clock}	Clock frequency	25	125	MHz
	Input clock duty cycle	40%	60%	
	Stabilization time†		1	ms

† Time required for the integrated PLL circuit to obtain phase lock of its feedback signal to its reference signal. For phase lock to be obtained, a fixed-frequency, fixed-phase reference signal must be present at CLK. Until phase lock is obtained, the specifications for propagation delay, skew, and jitter parameters given in the switching characteristics table are not applicable.

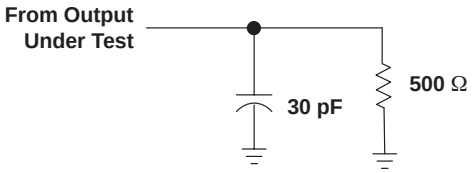
switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 30 pF (see Note 5 and Figures 1 and 2)‡

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 3.3 V ± 0.165 V			V_{CC} = 3.3 V ± 0.3 V			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	
$t_{phase\ error}$ reference (see Figure 3)	66 MHz < CLKIN↑ < 100 MHz	FBIN↑					−80...400		ps
$t_{phase\ error,\ -\ jitter,}$ (see Note 6)	CLKIN↑ = 100 MHz	FBIN↑	170		360		240		ps
$t_{sk(o)}$§	Any Y or FBOUT	Any Y or FBOUT						200	ps
$Jitter_{(pk-pk)}$	F(clkin > 66 MHz)	Any Y or FBOUT				−100		100	ps
Duty cycle	F(clkin ≤ 66 MHz)	Any Y or FBOUT				45%		55%	
	F(clkin > 66 MHz)	Any Y or FBOUT				43%		57%	
t_r		Any Y or FBOUT		1.1	1.5	0.7		1.6	ns
t_f		Any Y or FBOUT		0.8	1.3	0.5		1.5	ns

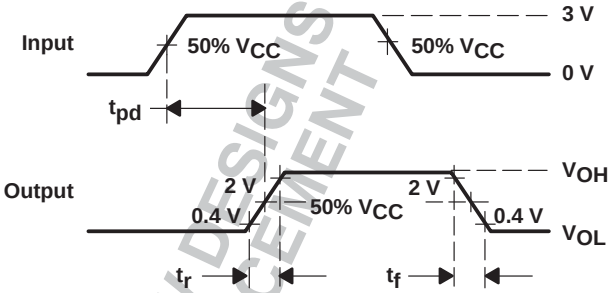
‡ These parameters are not production tested.
§ The $t_{sk(o)}$ specification is only valid for equal loading of all outputs.

NOTES: 5. The specifications for parameters in this table are applicable only after any appropriate stabilization time has elapsed.
6. Phase error does not include jitter. The total phase error is 70 ps to 460 ps for the 5% V_{CC} range.

PARAMETER MEASUREMENT INFORMATION



LOAD CIRCUIT



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES

NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 100 MHz, Z_O = 50 Ω, t_r ≤ 1.2 ns, t_f ≤ 1.2 ns.
C. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION

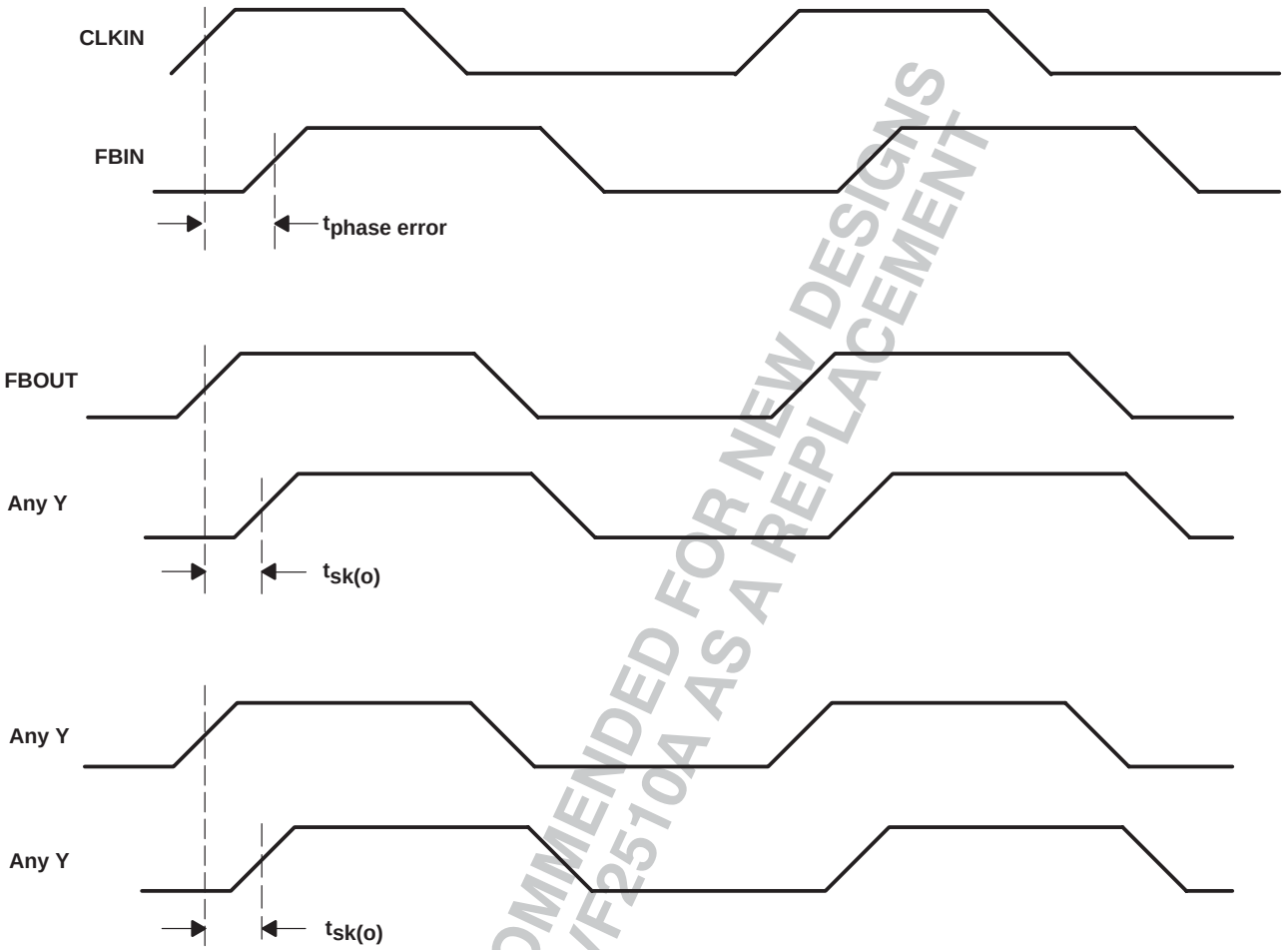


Figure 2. Phase Error and Skew Calculations

TYPICAL CHARACTERISTICS

PHASE ERROR
vs
CLOCK FREQUENCY

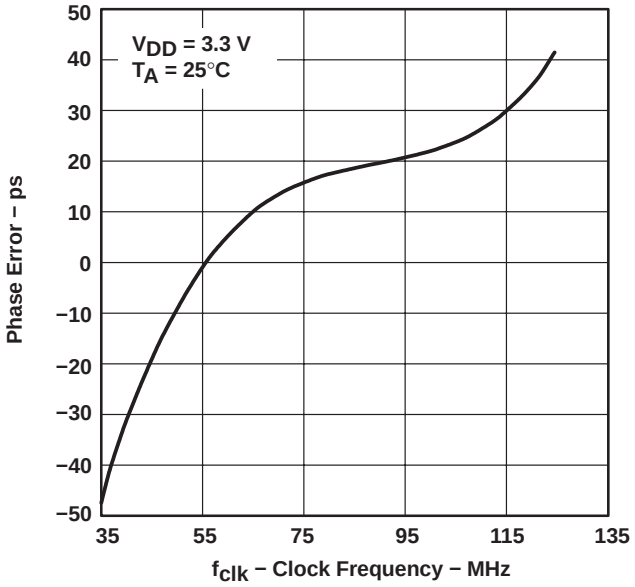


Figure 3

OUTPUT DUTY CYCLE
vs
CLOCK FREQUENCY

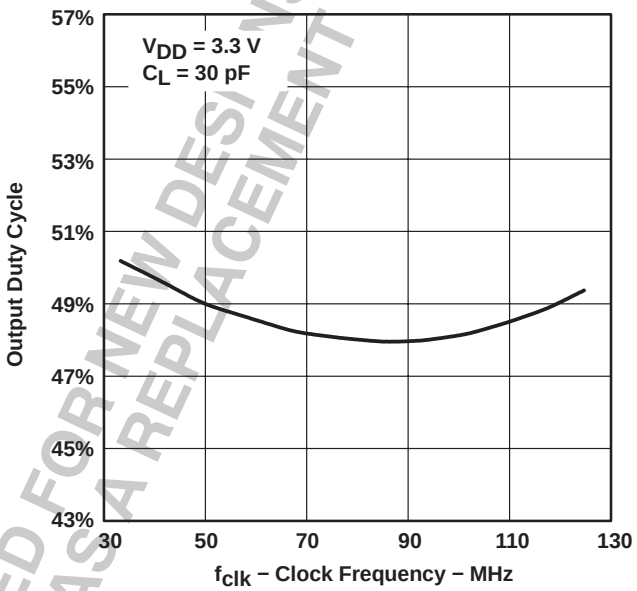


Figure 4

ANALOG SUPPLY CURRENT
vs
CLOCK FREQUENCY

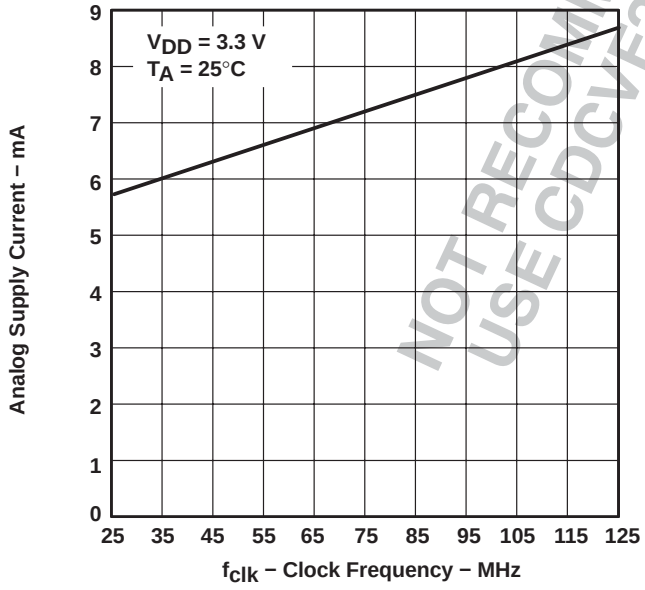


Figure 5

DYNAMIC SUPPLY CURRENT
vs
CLOCK FREQUENCY

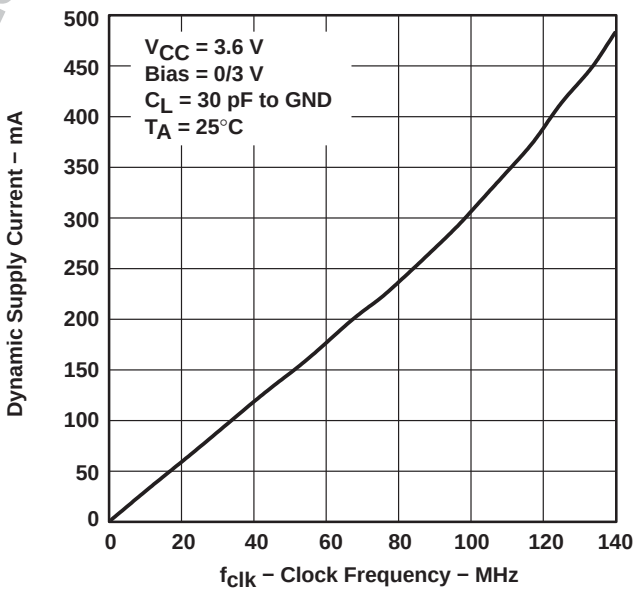
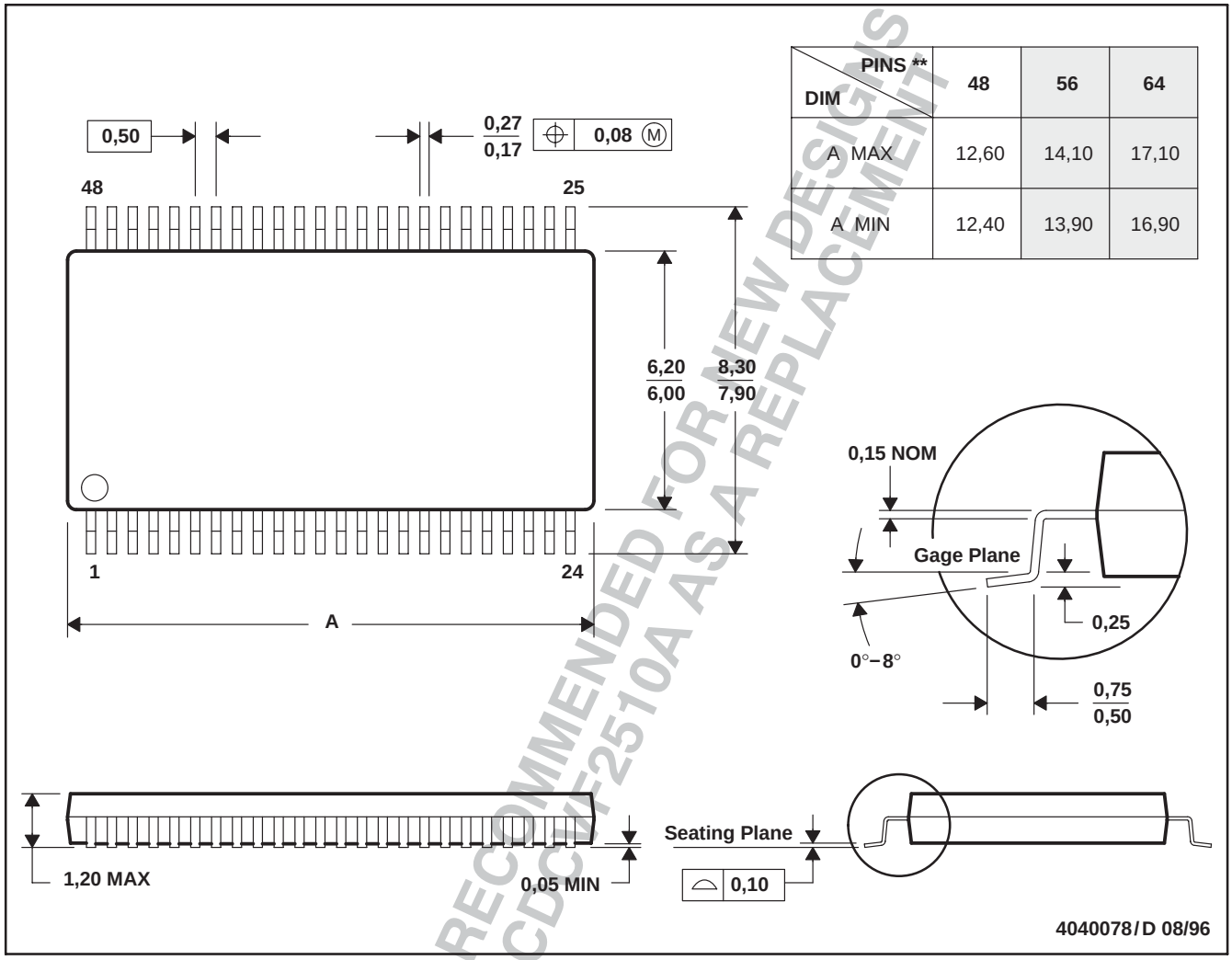


Figure 6

MECHANICAL INFORMATION

DGG (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

48 PIN SHOWN



DIM \ PINS **	48	56	64
A MAX	12,60	14,10	17,10
A MIN	12,40	13,90	16,90

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Falls within JEDEC MO-153

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
CDC516DGG	ACTIVE	TSSOP	DGG	48	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
CDC516DGGG4	ACTIVE	TSSOP	DGG	48	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
CDC516DGGR	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
CDC516DGGRG4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR

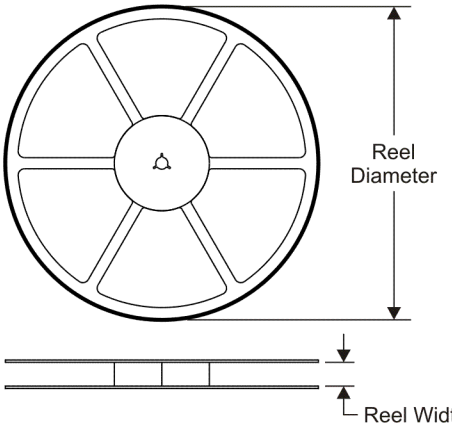
(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

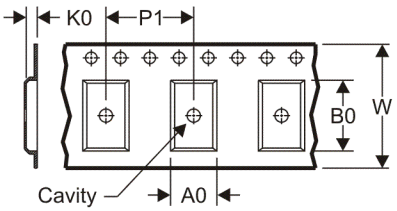
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

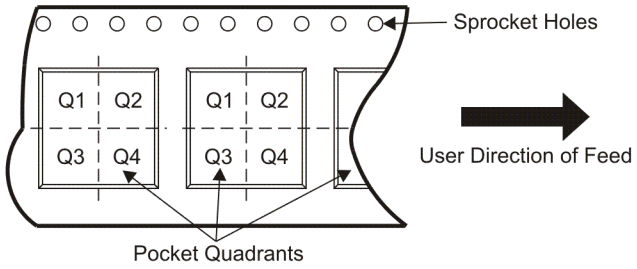


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

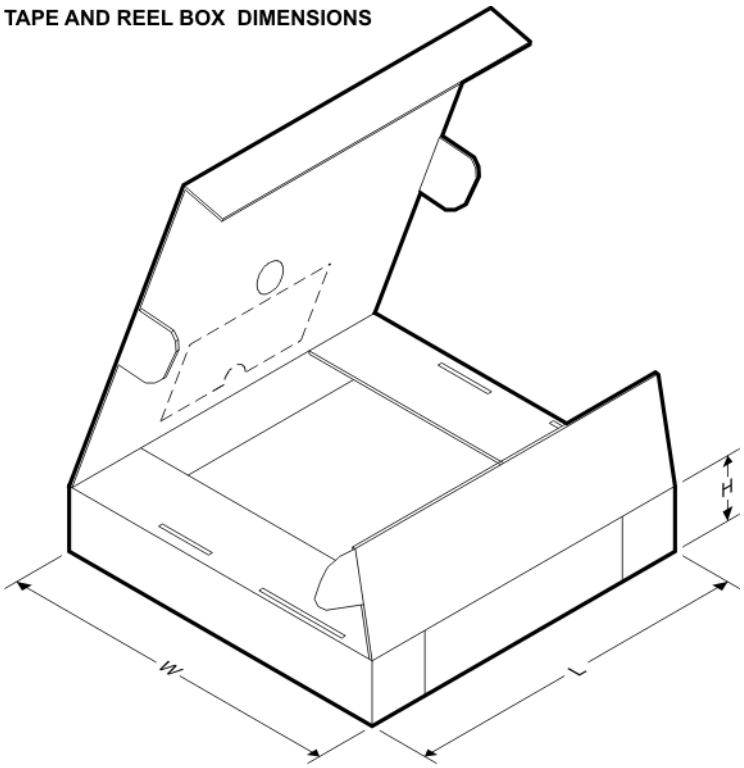
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CDC516DGGR	TSSOP	DGG	48	2000	330.0	24.4	8.6	15.8	1.8	12.0	24.0	Q1

TAPE AND REEL BOX DIMENSIONS

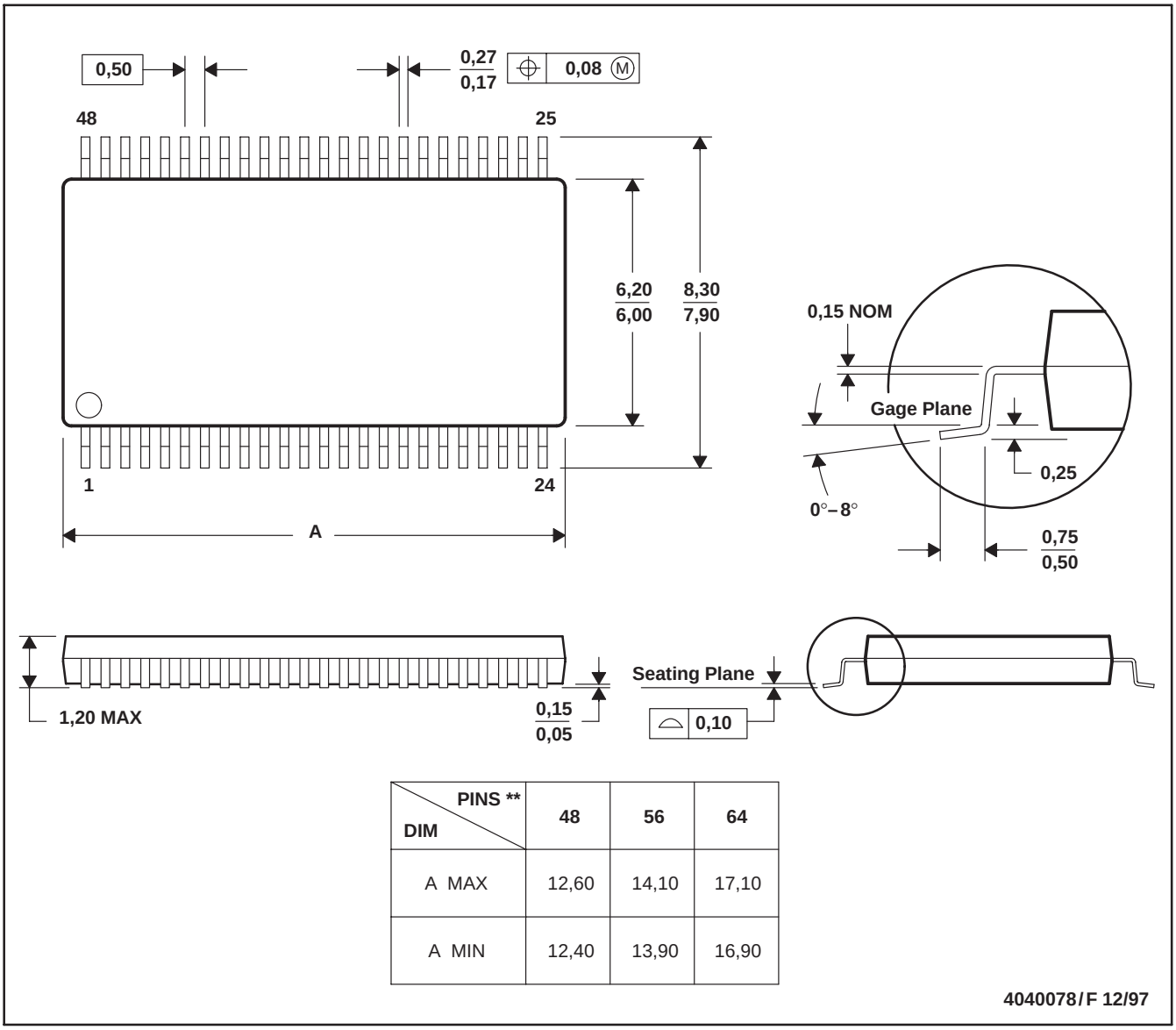


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CDC516DGGR	TSSOP	DGG	48	2000	346.0	346.0	41.0

DGG (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

48 PINS SHOWN



DIM \ PINS **	48	56	64
A MAX	12,60	14,10	17,10
A MIN	12,40	13,90	16,90

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold protrusion not to exceed 0,15.
D. Falls within JEDEC MO-153

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Logic	logic.ti.com	Military	www.ti.com/military
Power Mgmt	power.ti.com	Optical Networking	www.ti.com/opticalnetwork
Microcontrollers	microcontroller.ti.com	Security	www.ti.com/security
RFID	www.ti-rfid.com	Telephony	www.ti.com/telephony
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		Wireless	www.ti.com/wireless

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